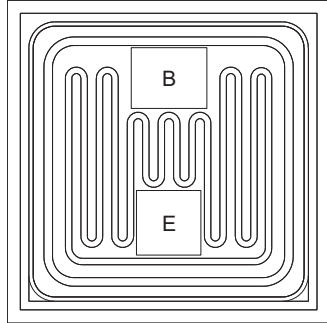


# CP310-CMPTA42

## NPN - High Voltage Transistor Die

The CP310-CMPTA42 is a silicon NPN transistor designed for high voltage applications.



BACKSIDE COLLECTOR R2

### MECHANICAL SPECIFICATIONS:

Die Size	26 x 26 MILS
Die Thickness	9.0 MILS
Base Bonding Pad Size	6.1 x 4.9 MILS
Emitter Bonding Pad Size	5.2 x 5.2 MILS
Top Side Metalization	Al – 30,000Å
Back Side Metalization	Au – 9,000Å
Scribe Alley Width	2.2 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	25,214

### MAXIMUM RATINGS: ( $T_A=25^\circ\text{C}$ )

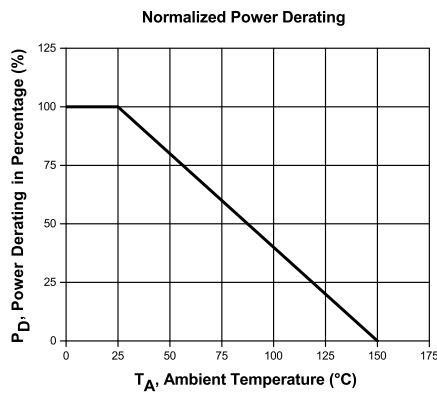
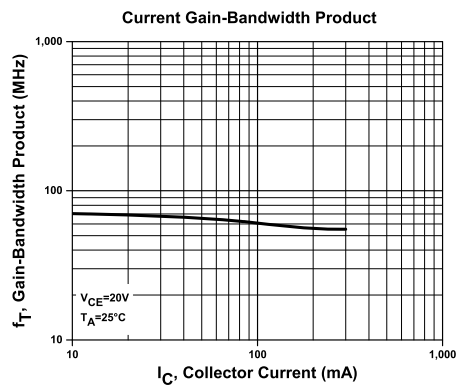
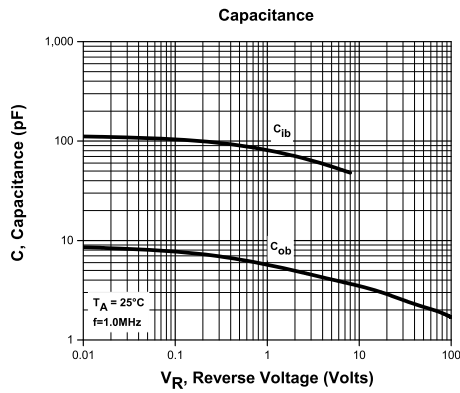
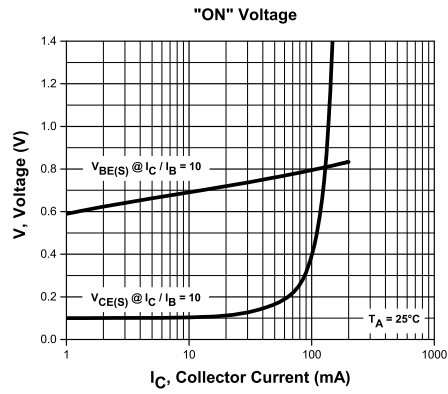
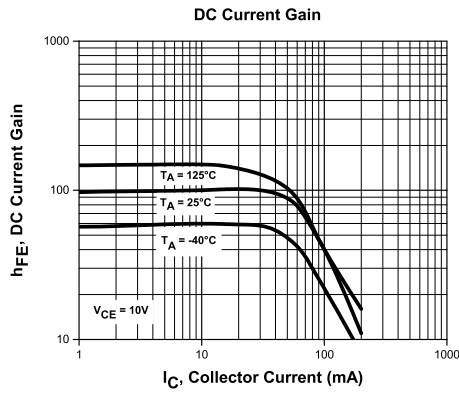
	SYMBOL		UNITS
Collector-Base Voltage	$V_{CBO}$	300	V
Collector-Emitter Voltage	$V_{CEO}$	300	V
Emitter-Base Voltage	$V_{EBO}$	6.0	V
Continuous Collector Current	$I_C$	500	mA
Operating and Storage Junction Temperature	$T_J, T_{stg}$	-65 to +150	$^\circ\text{C}$

### ELECTRICAL CHARACTERISTICS: ( $T_A=25^\circ\text{C}$ )

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
$I_{CBO}$	$V_{CB}=200\text{V}$		100	nA
$I_{EBO}$	$V_{EB}=6.0\text{V}$		100	nA
$BV_{CBO}$	$I_C=100\mu\text{A}$	300		V
$BV_{CEO}$	$I_C=1.0\text{mA}$	300		V
$BV_{EBO}$	$I_E=100\mu\text{A}$	6.0		V
$V_{CE(SAT)}$	$I_C=20\text{mA}, I_B=2.0\text{mA}$		0.5	V
$V_{BE(SAT)}$	$I_C=20\text{mA}, I_B=2.0\text{mA}$		0.9	V
$h_{FE}$	$V_{CE}=10\text{V}, I_C=1.0\text{mA}$	25		
$h_{FE}$	$V_{CE}=10\text{V}, I_C=10\text{mA}$	40		
$h_{FE}$	$V_{CE}=10\text{V}, I_C=30\text{mA}$	40		
$f_T$	$V_{CE}=20\text{V}, I_C=10\text{mA}, f=100\text{MHz}$	50		MHz
$C_{ob}$	$V_{CB}=20\text{V}, I_E=0, f=1.0\text{MHz}$		6.0	pF

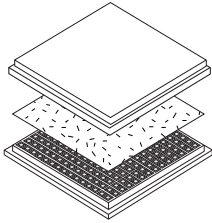
# CP310-CMPTA42

## Typical Electrical Characteristics



## BARE DIE PACKING OPTIONS

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### BARE DIE IN TRAY (WAFFLE) PACK

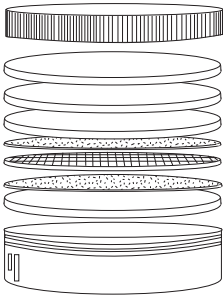
**CT:** Singulated die in tray (waffle) pack.

(example: CP211-PART NUMBER-CT)

**CM:** Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).

(example: CP211-PART NUMBER-CM)

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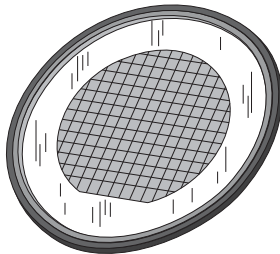


### UNSAWN WAFER

**WN:** Full wafer, unsawn, 100% tested with reject die inked.

(example: CP211-PART NUMBER-WN)

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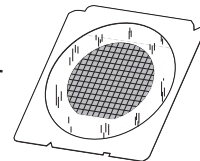


### SAWN WAFER ON PLASTIC RING

**WR:** Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.

(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



R1 (10-February 2017)

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



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### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

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### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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### CONTACT US

#### Corporate Headquarters & Customer Support Team

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